

General Description

The UM3015 is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The UM3015 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

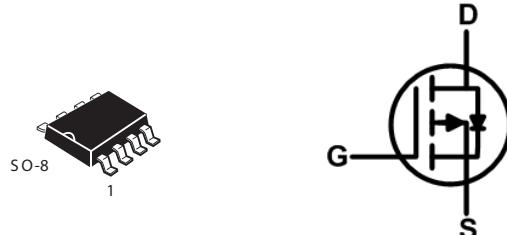
Product Summary

BVDSS	RDS(on)	ID
-30V	10.5mΩ	-10A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-10	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-8	A
I_{DM}	Pulsed Drain Current ²	-40	A
EAS	Single Pulse Avalanche Energy ³	408	mJ
I_{AS}	Avalanche Current	-55.4	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation ⁴	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	24	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.018	---	$\text{V}/^\circ\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{GS}=-10\text{V}$, $I_D=-10\text{A}$	---	8	10.5	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-8\text{A}$	---	14	18.5	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	5.04	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-10\text{A}$	---	25	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-15\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-10\text{A}$	---	30	42	nC
Q_{gs}	Gate-Source Charge		---	10	14	
Q_{gd}	Gate-Drain Charge		---	10.4	14.6	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=3.3\Omega$, $I_D=-10\text{A}$	---	9.4	19	ns
T_r	Rise Time		---	10.2	18	
$T_{d(off)}$	Turn-Off Delay Time		---	117	234	
T_f	Fall Time		---	24	48	
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	3448	4827	pF
C_{oss}	Output Capacitance		---	508	711	
C_{rss}	Reverse Transfer Capacitance		---	421	589	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	$V_{DD}=-25\text{V}$, $L=0.1\text{mH}$, $I_{AS}=-30\text{A}$	120	---	---	mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,6}	$V_G=V_D=0\text{V}$, Force Current	---	---	-10	A
I_{SM}	Pulsed Source Current ^{2,6}		---	---	-40	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-10\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$,	---	19.4	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	9.1	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=-25\text{V}$, $V_{GS}=-10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=-55.4\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

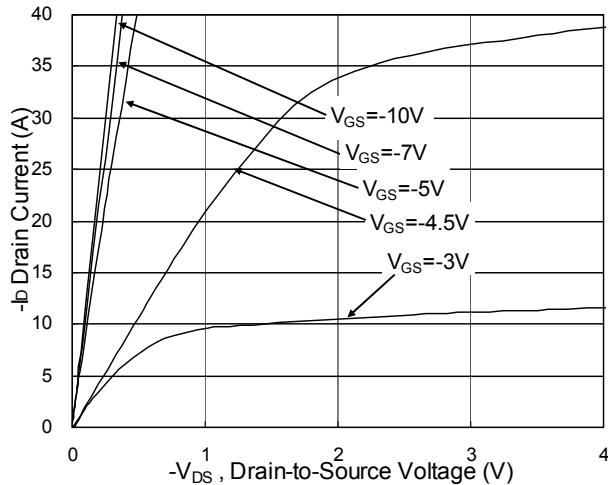


Fig.1 Typical Output Characteristics

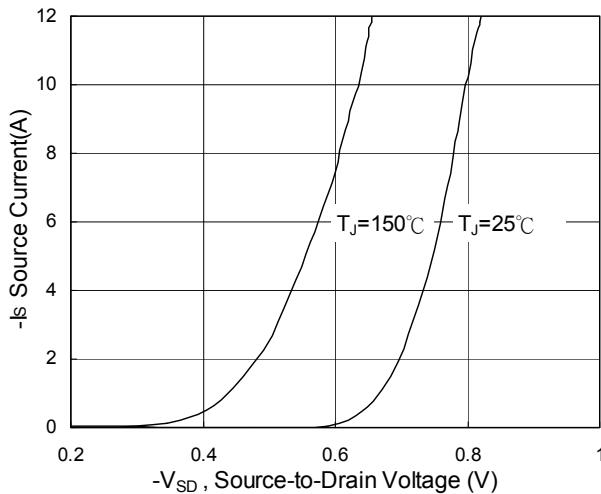


Fig.3 Forward Characteristics Of Reverse

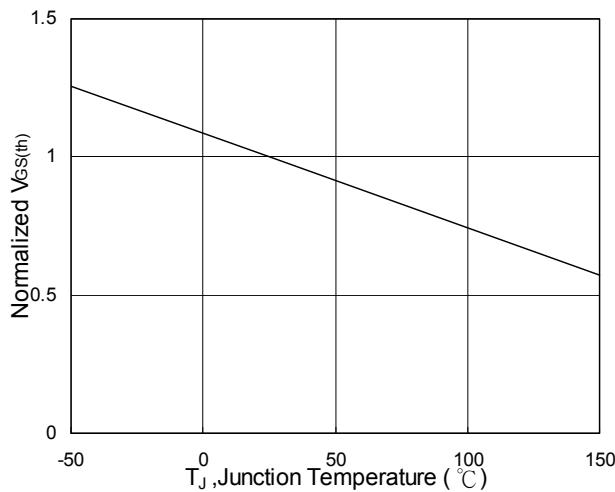


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

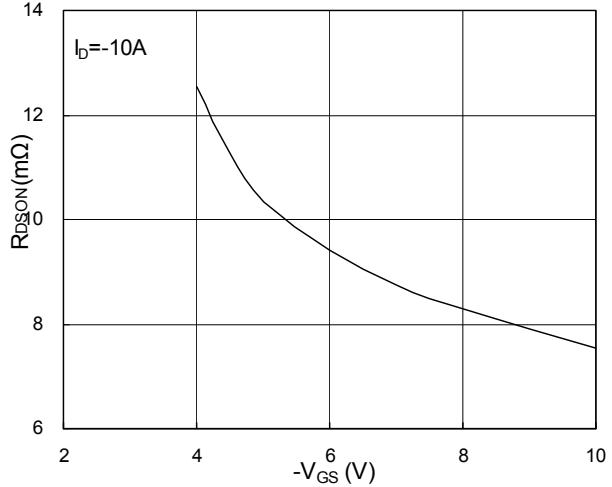


Fig.2 On-Resistance v.s Gate-Source

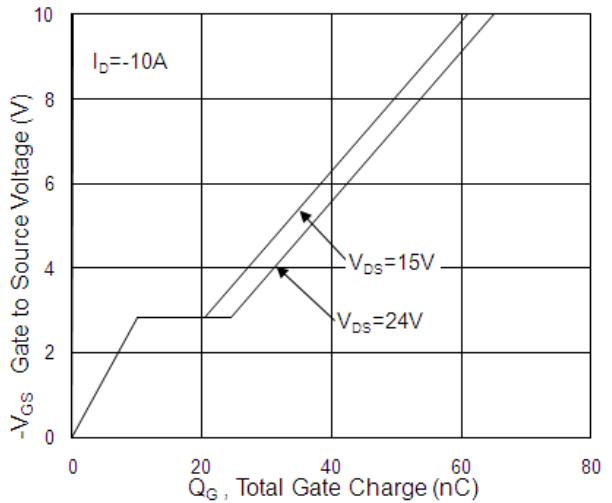


Fig.4 Gate-Charge Characteristics

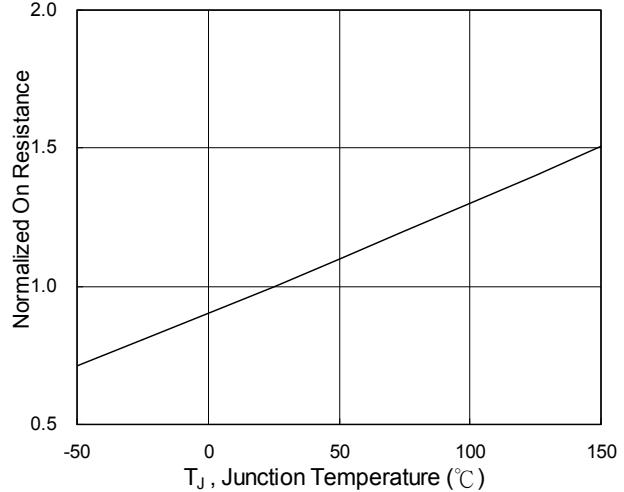


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

P-Ch 30V Fast Switching MOSFETs

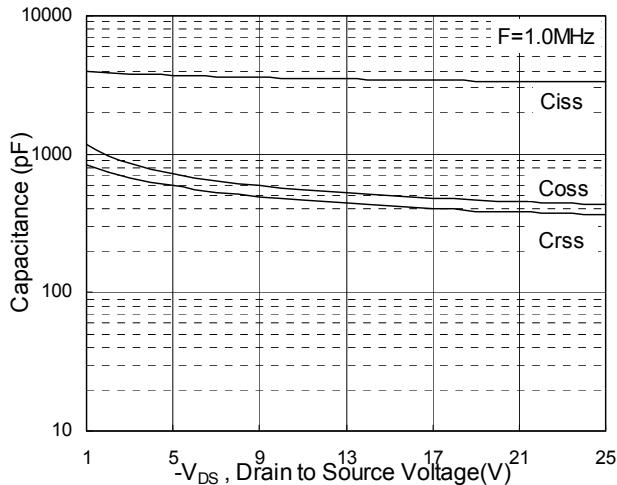


Fig.7 Capacitance

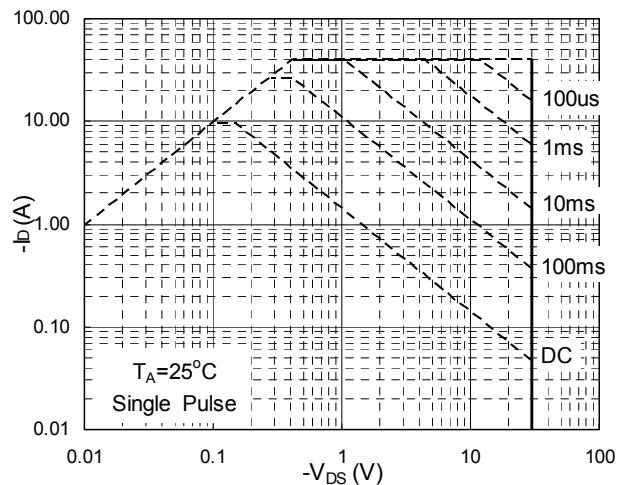


Fig.8 Safe Operating Area

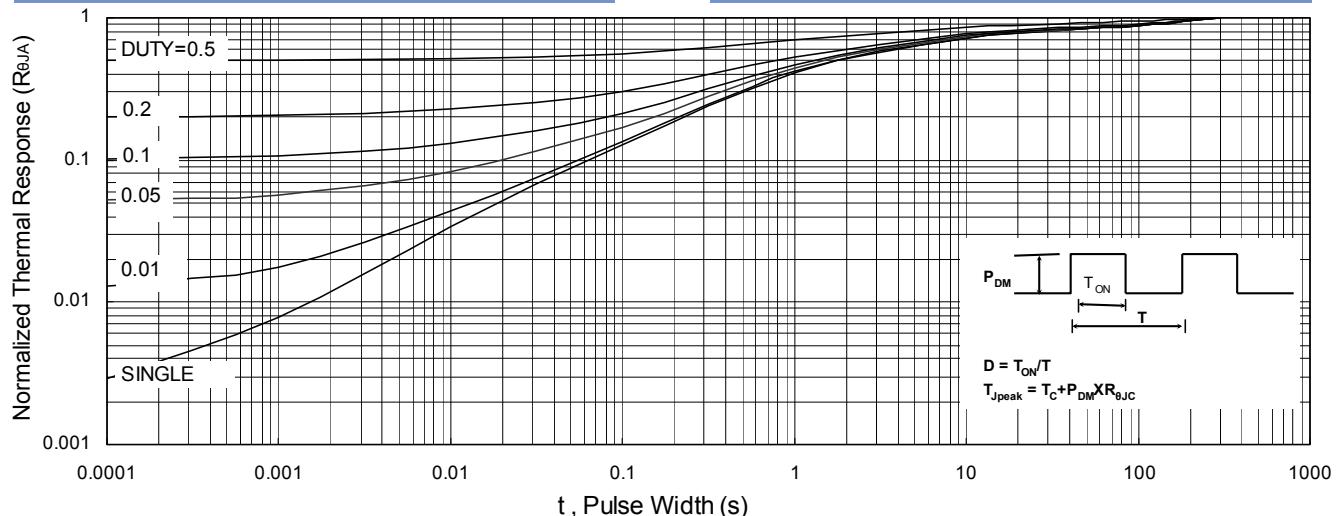


Fig.9 Normalized Maximum Transient Thermal Impedance

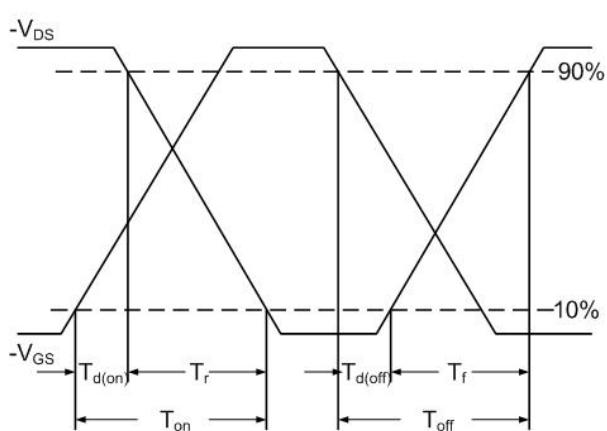


Fig.10 Switching Time Waveform

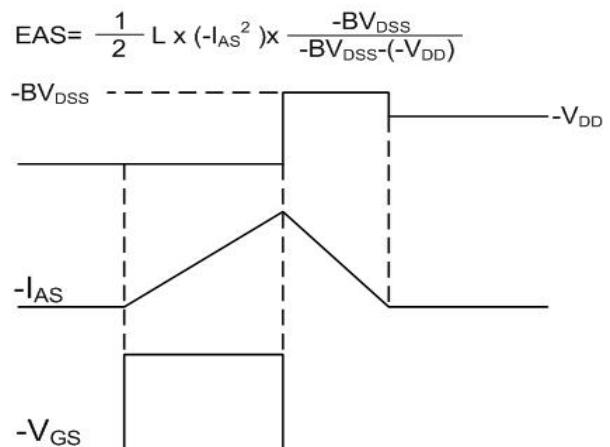


Fig.11 Unclamped Inductive Switching Waveform